

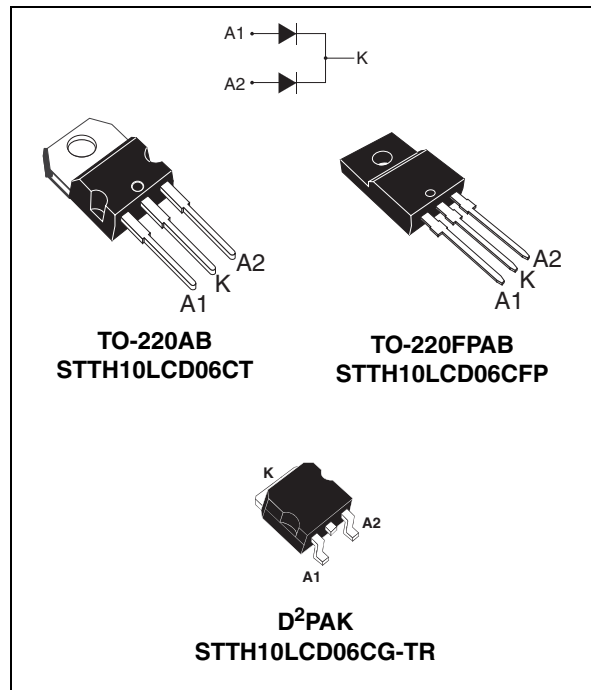
## Turbo 2 ultrafast - high voltage rectifier for SMPS

### Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces conduction and switching losses

### Description

The STTH10LCD06C uses ST Turbo2 technology. This device is specially suited for switching power supplies working with interleaved PFCs.



**Table 1. Device summary**

$I_{F(AV)}$	2 x 5A
$V_{RRM}$	600 V
$T_j$	175 °C
$V_F$ (typ)	1.25 V
$t_{rr}$ (max)	25 ns

# 1 Characteristics

**Table 2. Absolute ratings<sup>(1)</sup>**

Symbol	Parameter			Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage			600	V	
I <sub>F(RMS)</sub>	Forward current rms			20	A	
I <sub>F(AV)</sub>	Average forward current, δ = 0.5	T <sub>c</sub> = 130 °C	TO-220AB, D <sup>2</sup> PAK	Per diode	5	A
			Per device	10	A	
		T <sub>c</sub> = 100 °C	TO-220FPAB	Per diode	5	A
				Per device	10	A
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal		60	A	
T <sub>stg</sub>	Storage temperature range			-65 to + 175	°C	
T <sub>j</sub>	Maximum operating junction temperature <sup>(2)</sup>			175	°C	

1. Limiting values per diode at 25 °C, unless otherwise specified
2.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case(per diode)	TO-220AB, D <sup>2</sup> PAK	4.5	°C/W
		TO-220FPAB	7.5	

**Table 4. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>			1	μA
		T <sub>j</sub> = 150 °C			5	50	
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A			2	V
		T <sub>j</sub> = 150 °C			1.25	1.6	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 10 A			2.35	
		T <sub>j</sub> = 150 °C			1.55	2	

1. Pulse test: t<sub>p</sub> = 5 ms, δ < 2 %
2. Pulse test: t<sub>p</sub> = 380 μs, δ < 2 %

To evaluate the conduction losses use the following equation:

$$P = 1.2 \times I_{F(AV)} + 0.08 \times I_{F(RMS)}^2$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 0.5 \text{ A}$ , $I_{rr} = 0.25 \text{ A}$ , $I_R = 1 \text{ A}$ , $T_j = 25 \text{ }^\circ\text{C}$			25	ns
		$I_F = 1 \text{ A}$ , $di_F/dt = -50 \text{ A}/\mu\text{s}$ , $V_R = 30 \text{ V}$ , $T_j = 25 \text{ }^\circ\text{C}$		35	50	
$I_{RM}$	Reverse recovery current	$I_F = 5 \text{ A}$ , $di_F/dt = -50 \text{ A}/\mu\text{s}$ , $V_R = 400 \text{ V}$ , $T_j = 125 \text{ }^\circ\text{C}$		1.8	2.5	A
$t_{fr}$	Forward recovery time	$I_F = 5 \text{ A}$ , $di_F/dt = 100 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$ , $T_j = 25 \text{ }^\circ\text{C}$			100	ns
$V_{FP}$	Forward recovery voltage	$I_F = 5 \text{ A}$ , $di_F/dt = 100 \text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$ , $T_j = 25 \text{ }^\circ\text{C}$		5		V

Figure 1. Average forward power dissipation versus average forward current (per diode)

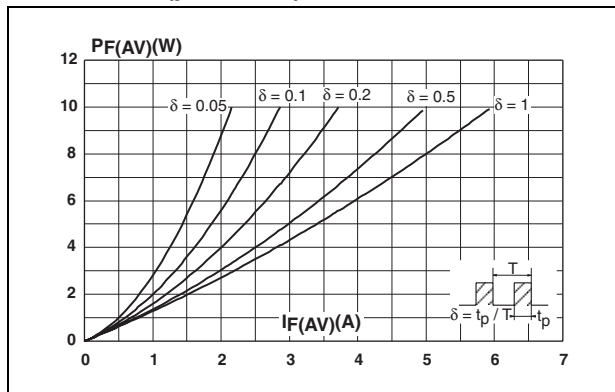


Figure 2. Forward voltage drop versus forward current (per diode)

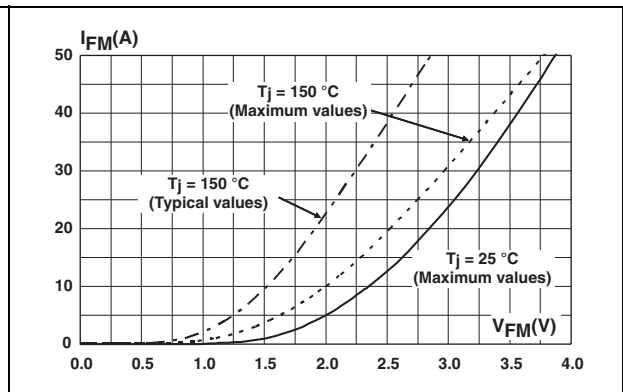


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration (TO-220AB, D<sup>2</sup>PAK)

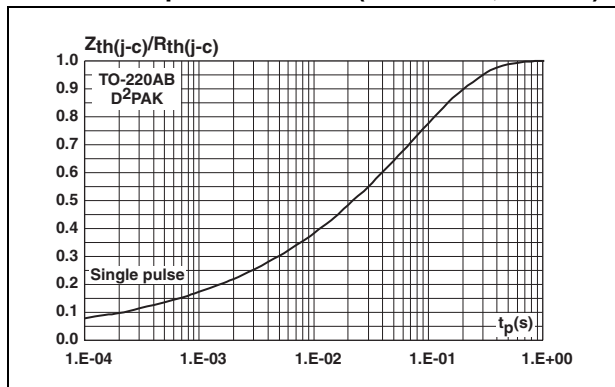
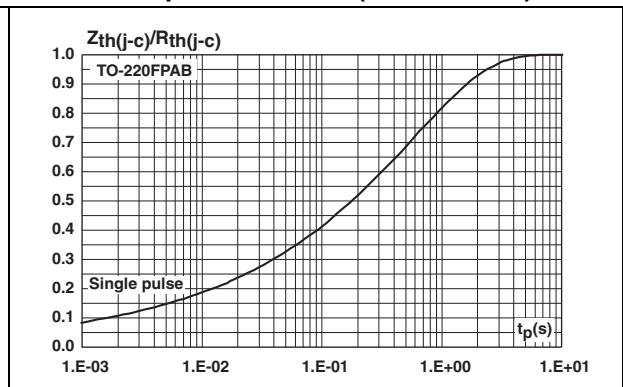
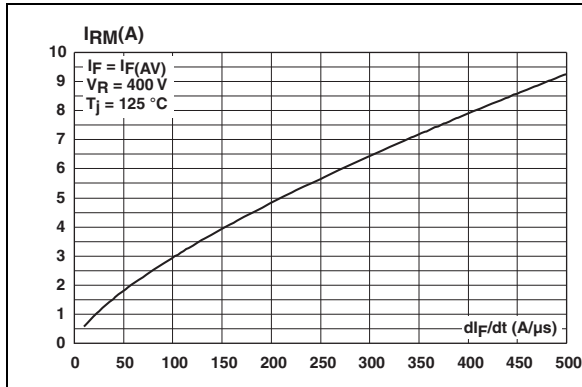


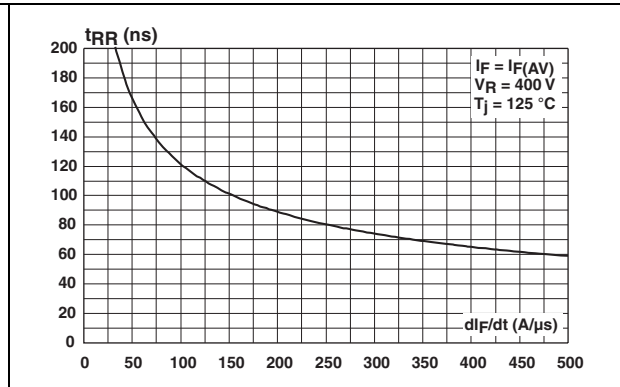
Figure 4. Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB)



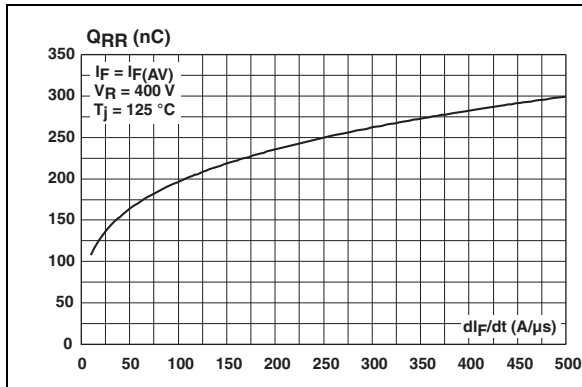
**Figure 5. Peak reverse recovery current versus  $di_F/dt$  (typical values, per diode)**



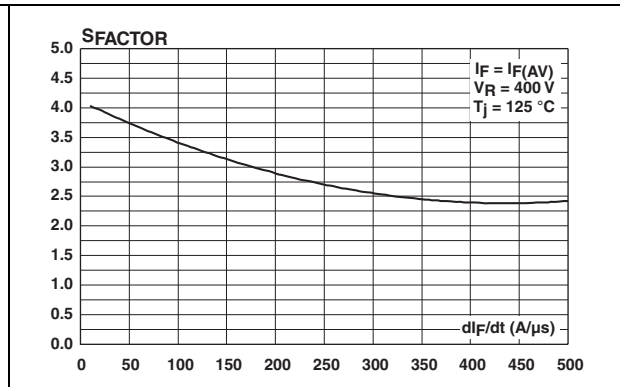
**Figure 6. Reverse recovery time versus  $di_F/dt$  (typical values, per diode)**



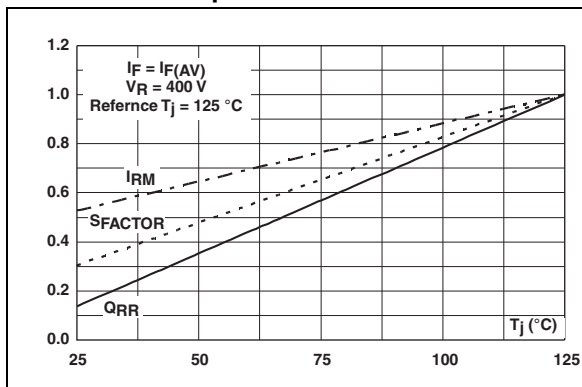
**Figure 7. Reverse recovery charges versus  $di_F/dt$  (typical values, per diode)**



**Figure 8. Reverse recovery softness factor versus  $di_F/dt$  (typical values, per diode)**



**Figure 9. Relative variations of dynamic parameters versus junction temperature**



**Figure 10. Transient peak forward voltage versus  $di_F/dt$  (typical values, per diode)**

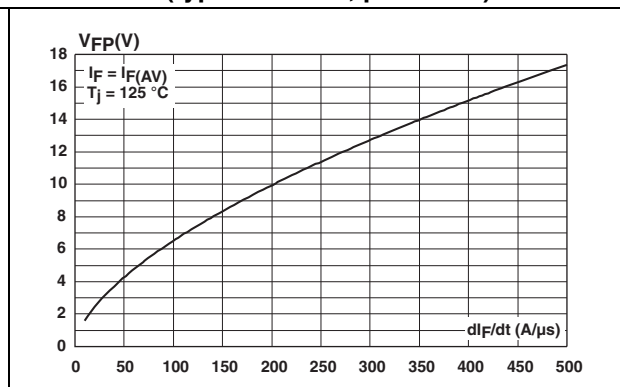


Figure 11. Forward recovery time versus  $di_F/dt$  (typical values, per diode) Figure 12. Junction capacitance versus reverse voltage applied (typical values, per diode)

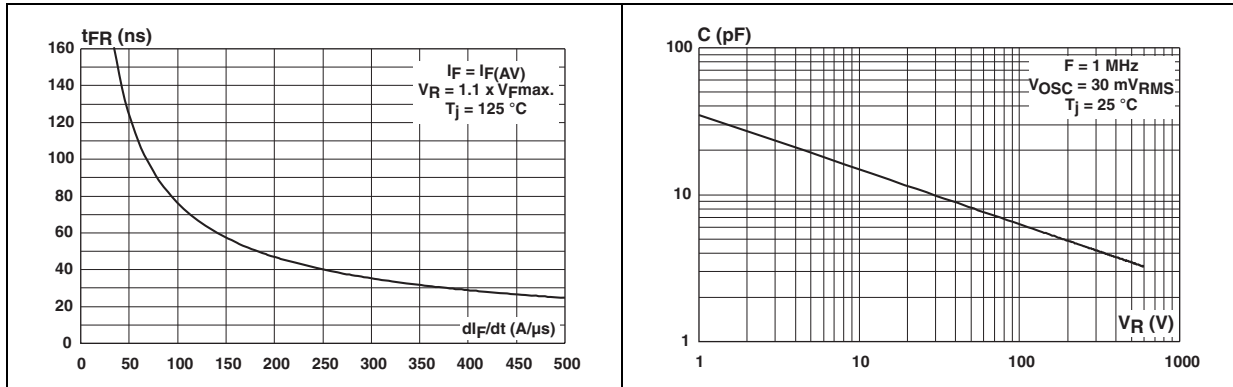
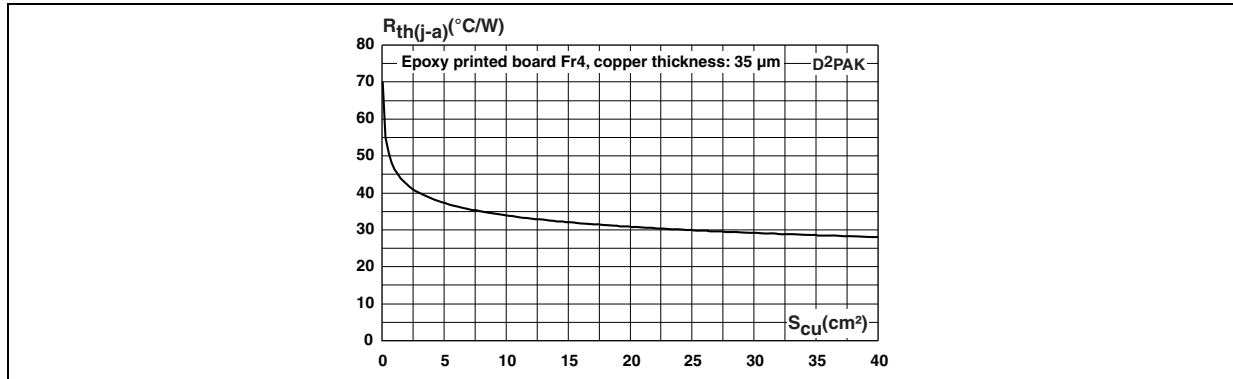


Figure 13. Thermal resistance junction to ambient versus copper surface under tab



## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

**Table 6. TO-220AB dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

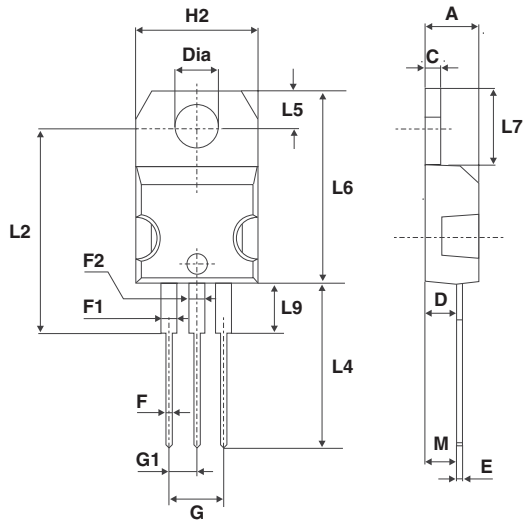


Table 7. TO-220FPAB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

Table 8. D<sup>2</sup>PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

\* FLAT ZONE NO LESS THAN 2mm



### 3 Ordering information

**Table 9. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH10LCD06CT	STTH10LCD06CT	TO-220AB	2.23 g	50	Tube
STTH10LCD06CG-TR	STTH10LCD06CG	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel
STTH10LCD06CFP	STTH10LCD06C	TO-220FPAB	2.04 g	50	Tube

### 4 Revision history

**Table 10. Document revision history**

Date	Revision	Changes
15-Jul-2009	1	First issue.
17-Jan-2011	2	Updated dimensions and graphic in <a href="#">Table 7</a> .
07-Apr-2011	3	Added (per diode) in <a href="#">Table 3</a> .

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